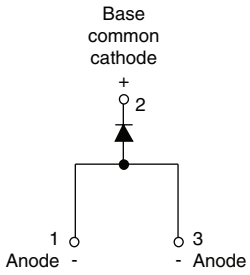
Surface Mountable
Fast Soft Recovery Diode, 8 A



D-PAK



FEATURES/DESCRIPTION

Available
RoHS* COMPLIANT

The 8EWF..SPbF fast soft recovery rectifier series has been optimized for combined short reverse recovery time, low forward voltage drop and low leakage current.

The glass passivation ensures stable reliable operation in the most severe temperature and power cycling conditions.

This series is designed and qualified for industrial level and lead (Pb)-free.

PRODUCT SUMMARY	
V_F at 8 A	< 1.3 V
t_{rr}	80 ns
V_{RRM}	1000/1200 V

APPLICATIONS

- Output rectification and freewheeling diode in inverters, choppers and converters
- Input rectifications where severe restrictions on conducted EMI should be met

MAJOR RATINGS AND CHARACTERISTICS			
SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Sinusoidal waveform	8	A
V_{RRM}		1000/1200	V
I_{FSM}		170	A
V_F	8 A, T_J = 25 °C	1.3	V
t_{rr}	1 A, 100 A/µs	80	ns
T_J	Range	- 40 to 150	°C

VOLTAGE RATINGS			
PART NUMBER	V_{RRM}, MAXIMUM PEAK REVERSE VOLTAGE V	V_{RSM}, MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I_{RRM} AT 150 °C mA
8EWF10SPbF	1000	1100	4
8EWF12SPbF	1200	1300	

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current	$I_{F(AV)}$	T_C = 94 °C, 180° conduction half sine wave	8	A
Maximum peak one cycle non-repetitive surge current	I_{FSM}	10 ms sine pulse, rated V_{RRM} applied	170	
		10 ms sine pulse, no voltage reapplied	200	
Maximum I^2t for fusing	I^2t	10 ms sine pulse, rated V_{RRM} applied	144	A^2s
		10 ms sine pulse, no voltage reapplied	200	
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	t = 0.1 to 10 ms, no voltage reapplied	2000	$A^2\sqrt{s}$

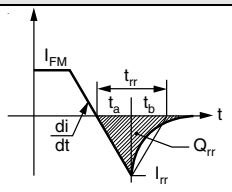
* Pb containing terminations are not RoHS compliant, exemptions may apply

ELECTRICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop	V_{FM}	8 A, T_J = 25 °C		1.3	V
Forward slope resistance	r_t	T_J = 150 °C		25.6	mΩ
Threshold voltage	$V_{F(TO)}$			0.93	V
Maximum reverse leakage current	I_{RM}	T_J = 25 °C	V_R = Rated V_{RRM}	0.1	mA
		T_J = 150 °C		4	

RECOVERY CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Reverse recovery time	t_{rr}	I_F at 8 Apk 25 A/µs T_J = 25 °C	270	ns
Reverse recovery current	I_{rr}		4.2	A
Reverse recovery charge	Q_{rr}		1	µC
Snap factor	S		0.6	



THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		- 40 to 150	°C
Maximum thermal resistance, junction to case	R_{thJC}	DC operation	2.5	°C/W
Typical thermal resistance, junction to ambient (PCB mount)	R_{thJA} (1)		50	
Soldering temperature	T_S	For 10 seconds	240	°C
Approximate weight			1	g
			0.03	oz.
Marking device		Case style D-PAK (TO-252AA)	8EWF12S	

Note

(1) When mounted on 1" square (650 mm^2) PCB of FR-4 or G-10 material 4 oz. (140 µm) copper 40 °C/W
For recommended footprint and soldering techniques refer to application note #AN-994

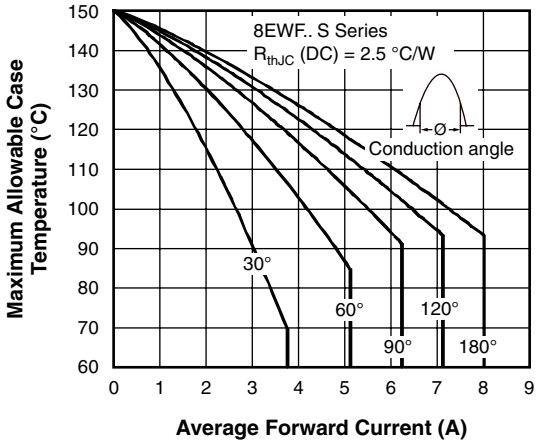


Fig. 1 - Current Rating Characteristics

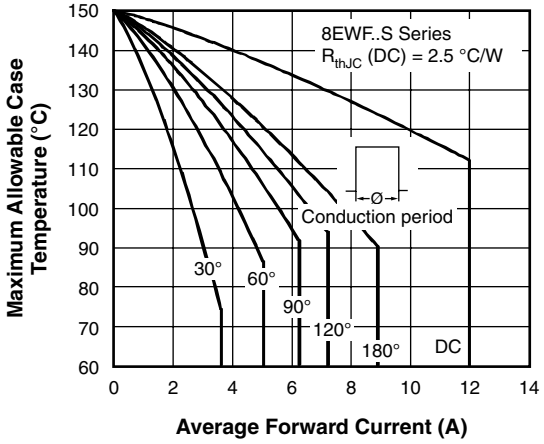


Fig. 2 - Current Rating Characteristics

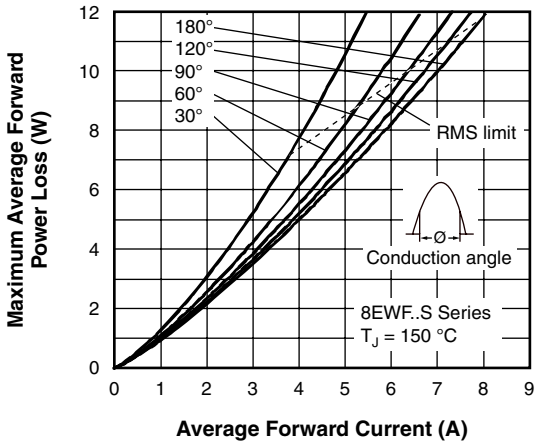


Fig. 3 - Forward Power Loss Characteristics

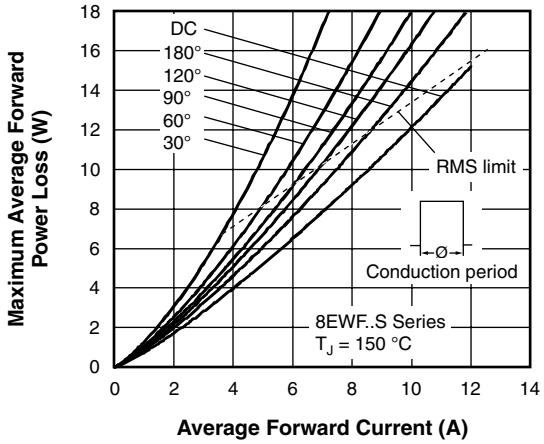


Fig. 4 - Forward Power Loss Characteristics

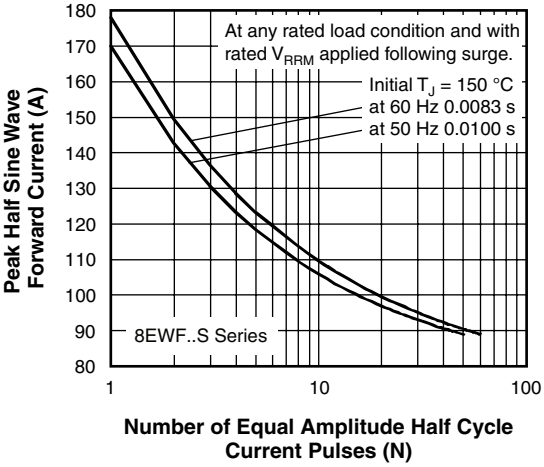


Fig. 5 - Maximum Non-Repetitive Surge Current

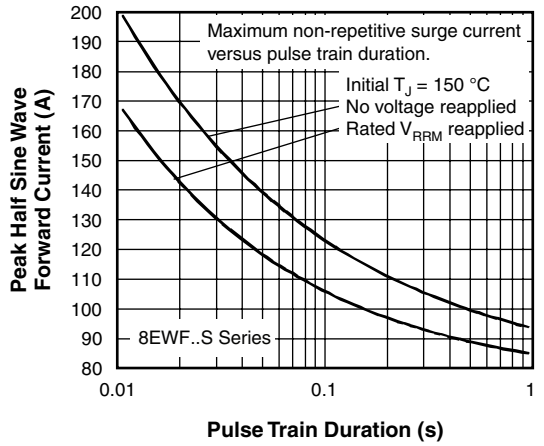


Fig. 6 - Maximum Non-Repetitive Surge Current

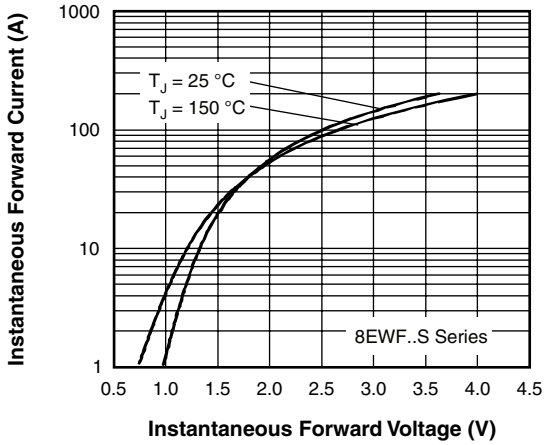


Fig. 7 - Forward Voltage Drop Characteristics

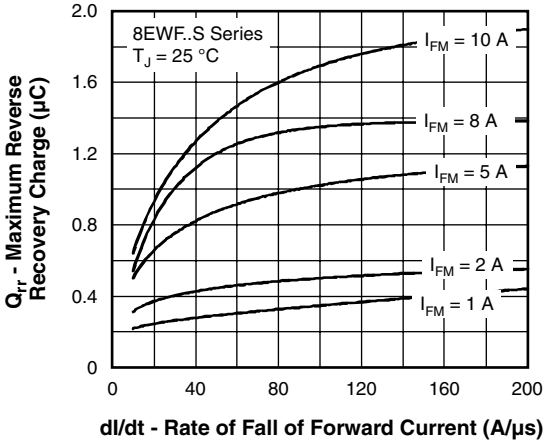


Fig. 10 - Recovery Charge Characteristics, T_J = 25 °C

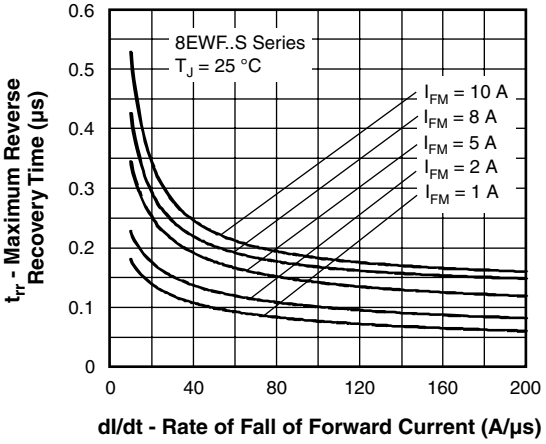


Fig. 8 - Recovery Time Characteristics, T_J = 25 °C

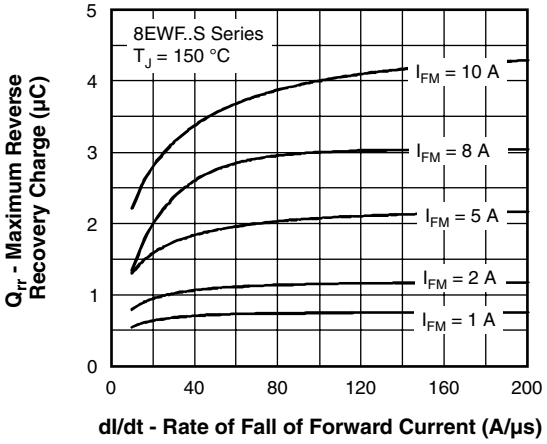


Fig. 11 - Recovery Charge Characteristics, T_J = 150 °C

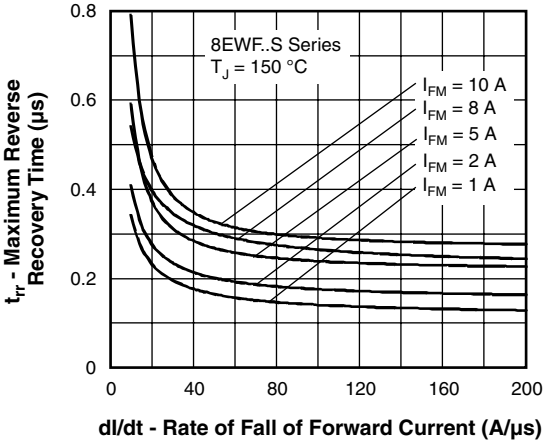


Fig. 9 - Recovery Time Characteristics, T_J = 150 °C

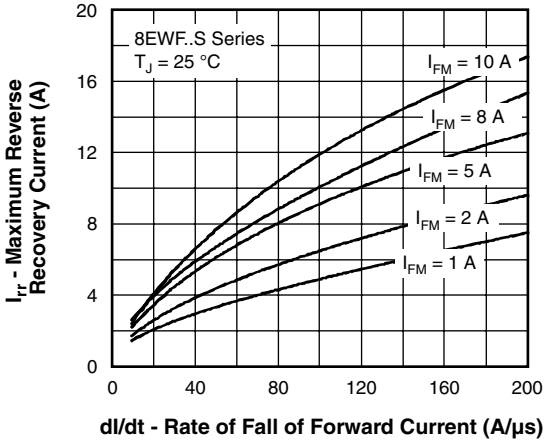


Fig. 12 - Recovery Current Characteristics, T_J = 25 °C

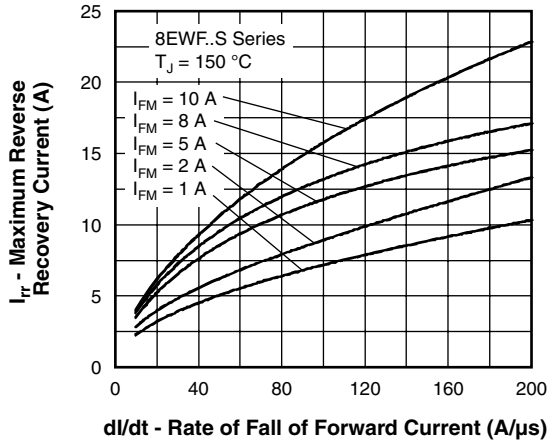


Fig. 13 - Recovery Current Characteristics, T_J = 150 °C

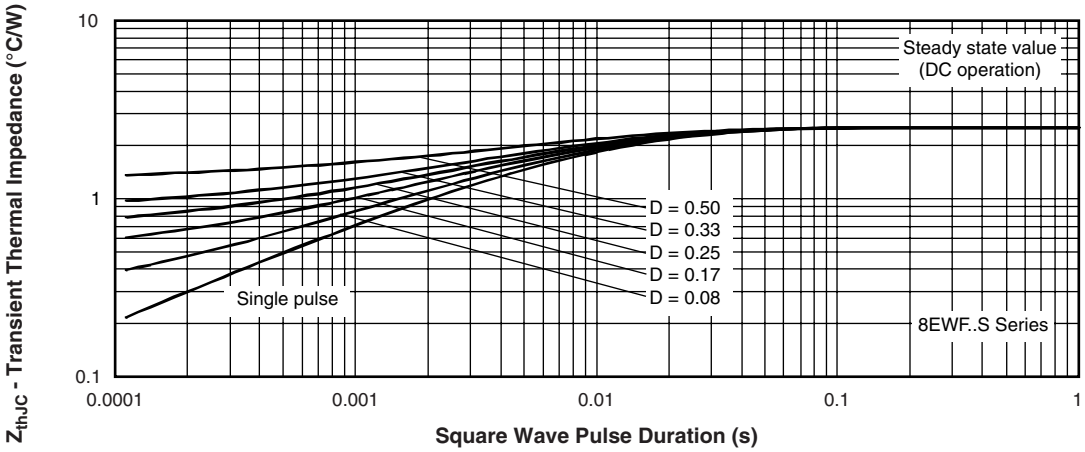
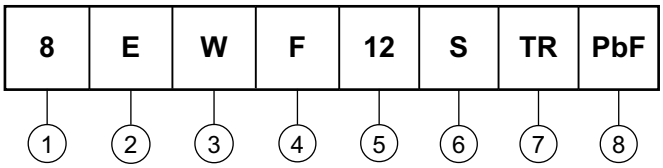


Fig. 14 - Thermal Impedance Z_{thJC} Characteristics

ORDERING INFORMATION TABLE

Device code



1 - Current rating (8 = 8 A)

2 - Circuit configuration:
E = Single diode

3 - Package:
W = D-PAK

4 - Type of silicon:
F = Fast soft recovery rectifier

5 - Voltage code x 100 = V_{RRM}
10 = 1000 V
12 = 1200 V

6 - S = Surface mountable

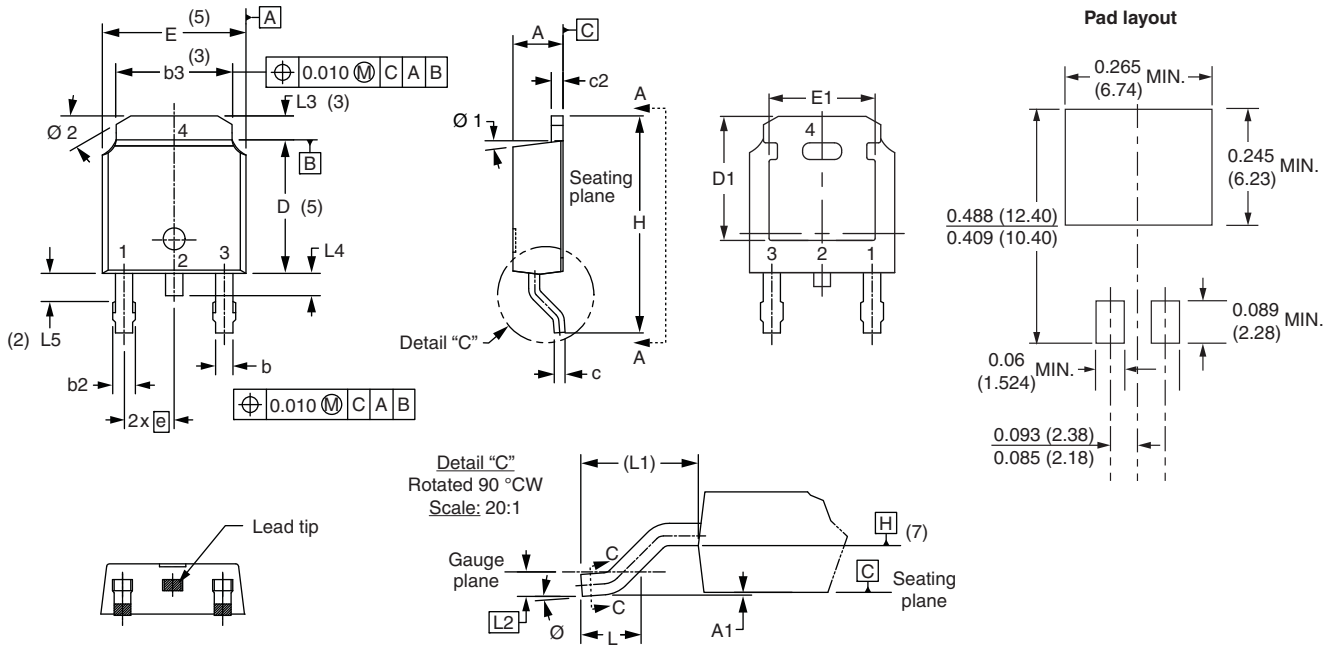
7 - • TR = Tape and reel
• TRR = Tape and reel (right oriented)
• TRL = Tape and reel (left oriented)

8 - • None = Standard production
• PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS	
Dimensions	http://www.vishay.com/doc?95016
Part marking information	http://www.vishay.com/doc?95059
Packaging information	http://www.vishay.com/doc?95033

D-PAK (TO-252AA)

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	0.086	0.094	
A1	-	0.13	-	0.005	
b	0.64	0.89	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	3
c	0.46	0.61	0.018	0.024	
c2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	5
D1	5.21	-	0.205	-	3
E	6.35	6.73	0.250	0.265	5
E1	4.32	-	0.170	-	3

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
e	2.29 BSC		0.090 BSC		
H	9.40	10.41	0.370	0.410	
L	1.40	1.78	0.055	0.070	
L1	2.74 BSC		0.108 REF.		
L2	0.51 BSC		0.020 BSC		
L3	0.89	1.27	0.035	0.050	3
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	2
Ø	0°	10°	0°	10°	
Ø1	0°	15°	0°	15°	
Ø2	25°	35°	25°	35°	

Notes

(1) Dimensioning and tolerancing as per ASME Y14.5M-1994
(2) Lead dimension uncontrolled in L5
(3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
(4) Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip
(5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
(6) Dimension b1 and c1 applied to base metal only
(7) Datum A and B to be determined at datum plane H
(8) Outline conforms to JEDEC outline TO-252AA

For technical questions within your region: DiodesAmericas@vishay.com, DiodesAsia@vishay.com, DiodesEurope@vishay.com

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